

RoHS

Specification

规格书

Customer Name: _____

客户名称:

Customer P/N: _____

客户品号:

Product Type: KDS-3528AP2SD1R8R

产品型号:

Sending Date: 2016.8.20

送样日期:

Client approval 客户审核			KD approval 科迪光电审核		
Approval 核准	Audit 确认	Confirmation 制作	Approval 核准	Audit 确认	Confirmation 制作
			<i>Fayao Wu</i>	<i>Wen</i>	<i>Li dankui</i>
☐ Qualified 接受			DATE: 日期 :2016.8.20		
☐ Disqualified 不接受					

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传真: 0572-6178998

PAplications (应用)

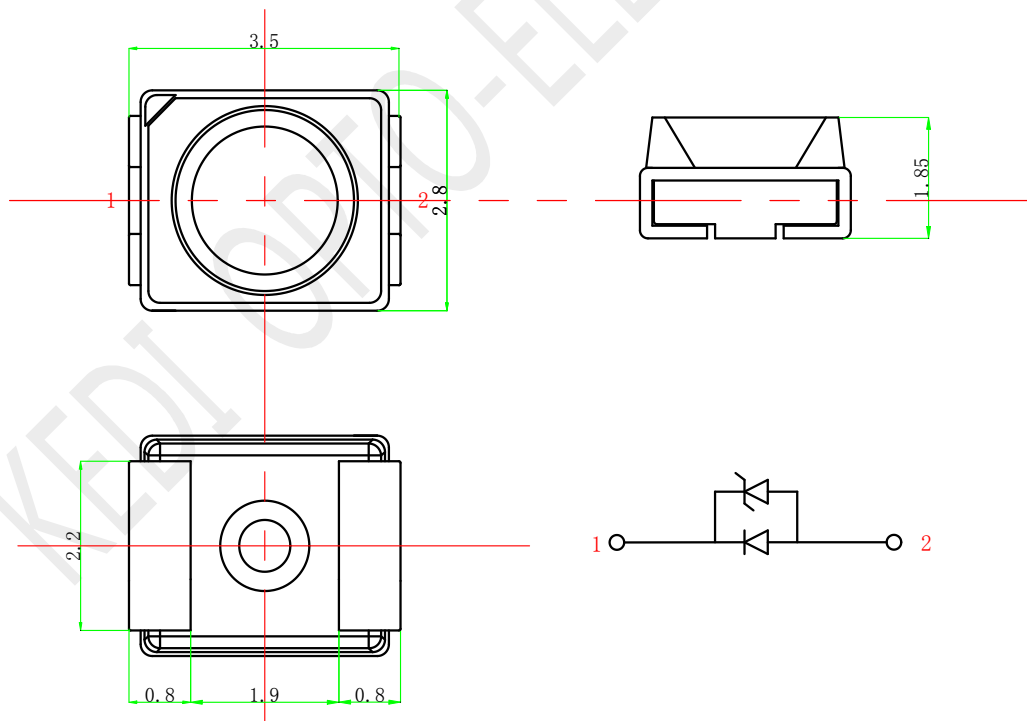
- Automotive lighting (汽车照明)
- Indoor display (室内显示)
- Backlight for LCD, switch and Symbol, display (LCD 背光、转换器, 开关和标志, 显示器等)
- General use (一般应用)

Description (描述)

The White LED which was fabricated using a blue chip and the phosphor

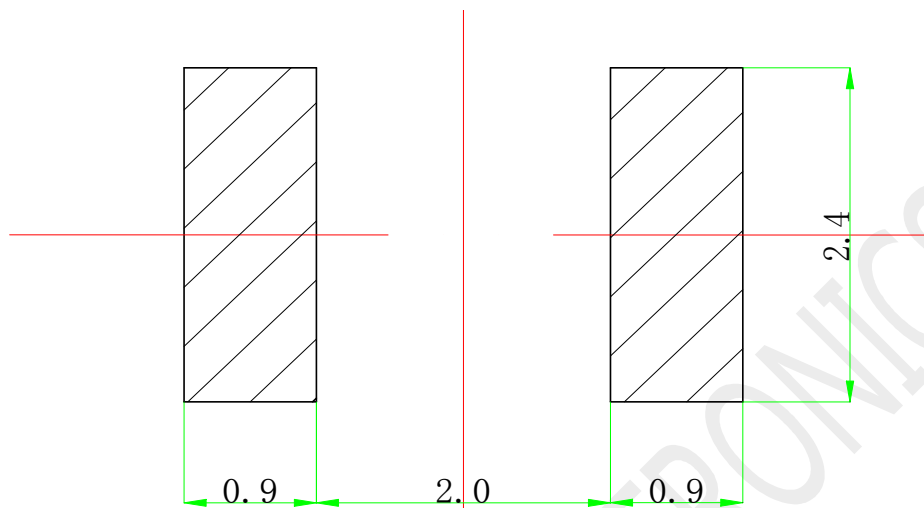
白光 LED 由蓝光芯片与荧光粉激发而成

Package Dimensions (封装尺寸)



Recommended Soldering Pattern

(建议焊盘尺寸图)



Notes: (备注)

1. All dimension units are millimeters. (所有标注尺寸单位为毫米)
2. All dimension tolerance is $\pm 0.15\text{mm}$ unless otherwise noted. (除特别标注外, 所有尺寸允许公差 $\pm 0.15\text{mm}$)

Features(特征)

1. PLCC-2 Package.(PLCC-2 封装)
2. Extremely wide viewing angle . (宽的发光角度)
3. Suitable for all SMT assembly and solder process. (适用于所有的 SMT 组装和焊接工艺)
4. Available on tape and reel. (适用于载带及卷轴)
5. Moisture sensitivity level: Level 4. (防潮等级 Level 4)
6. Package: 2000pcs/reel..(包装每卷 2000PCS)
7. Compliance with RoHS and REACH (RoHS/REACH 认证)
8. Qualified AEC-Q102(汽车应用认证)
9. ESD: 8KV(抗静电 8KV)

Electrical / Optical Characteristics at Ta=25° C 电性与光学特性)

性能参数 Characteristics	符号 Symbol	条件 Test Condition	最小值 Minimum	典型值 Typical	最大值 Maximum	单位 Unit
顺向电压 Forward voltage	Vf	I _F =20mA	2.6	3.0	3.4	V
反向电流 Reverse Current	I _r	V _r =5V	---	---	1	μA
CCT 色温	TC	I _F =20mA	5700	6000	6300	K
CIE	X	I _F =20mA	---	0.319	---	
	Y		---	0.347	---	
光通量 Luminous Flux	Φ	I _F =20mA	6	7	8	Lm
半功率视 Half-Intensity beam angle	2θ _{1/2}	I _F =20mA	---	120	---	Deg
显色指数 CRI	Ra	I _F =20mA		---		
光效 Lumen Efficacy	lm/w	I _F =20mA	100	---		Lm/w

Note:(备注)

- 2θ_{1/2} is the angle from optical centerline where the luminous intensity is 1/2 the optical centerline value.
2θ_{1/2}是半值角,指光强是光学中心线光强的 1/2 处到光学中心线的角度
- The above luminous flux measurement allowance tolerance is ±10%.
上述发光通量的测试允许公差为 ±10%
- The above Color Rendering Index measurement allowance tolerance is ±2
以上显色性指数的测试允许公差为±2
- The above forward voltage measurement allowance tolerance is ±0.1V.
以上所示电压测量误差±0.1V
- The above color coordinates measurement allowance tolerance is ±0.003.
以上所示坐标测量误差±0.003

Absolute Maximum Ratings at Ta=25° C 绝对最大额定值

Parameter (参数)	Symbol (符号)	Rating (值)	Units (单位)
Power Dissipation (功耗)	Pd	102	mW
Forward Current (正向电流)	IF	60	mA
Peak Forward Current [1] (峰值正向电流)	IFP	80	mA
Reverse Voltage (反向电压)	VR	7	V
Electrostatic Discharge (HBM) (人体模式抗静电)	ESD	8000	V
Operating Temperature (操作温度)	Topr	-40 ~ +110	°C
Storage Temperature (保存温度)	Tstg	-40 ~ +125	°C
Thermal Resistance (Junction / Solderingpoint) 热阻	Rthj-s	15	°C/W
Junction Temperature 结温	Tj	125	°C

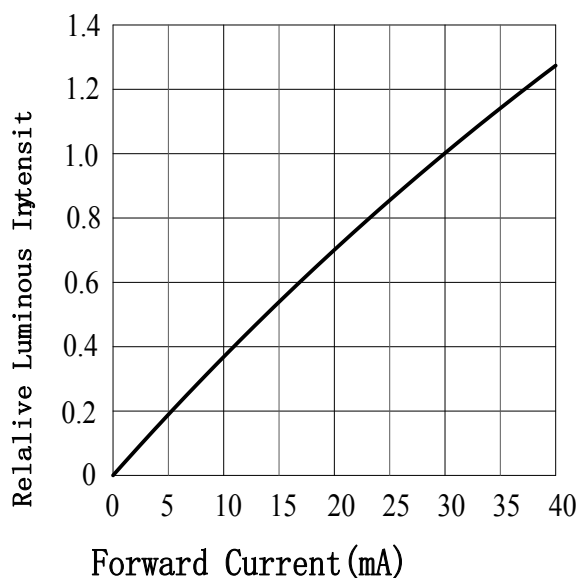
Note: (备注)

1/10 Duty cycle, 0.1ms pulse width. (脉宽 0.1ms, 周期 1/10)

Typical optical characteristics curves 典型光学特性曲线

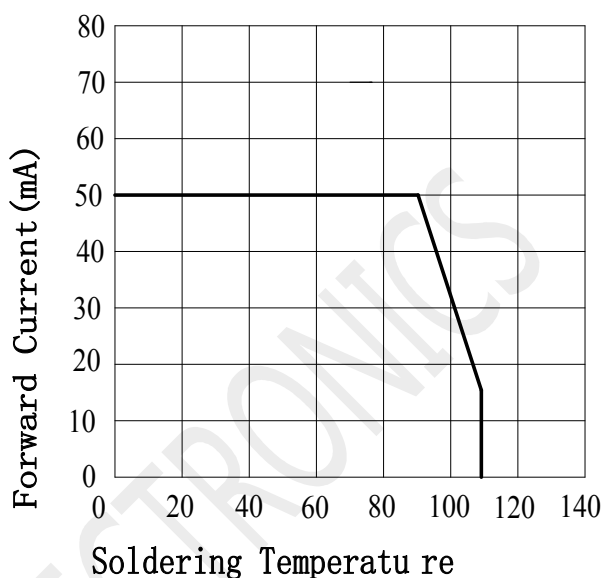
Forward Current VS. Relative Intensity

正向电流与相对光强特性曲线



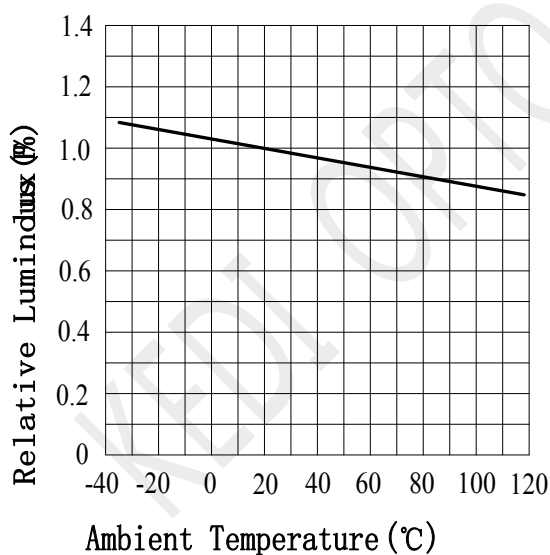
Soldering Temperature vs. Forward Current

焊盘温度与正向电流特性曲线



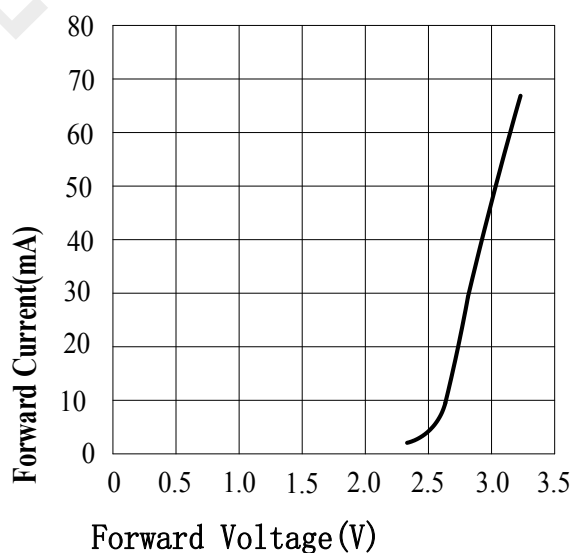
Ambient Temperature VS. Relative Intensity

环境温度与相对光强特性曲线



Forward Voltage VS. Forward Current

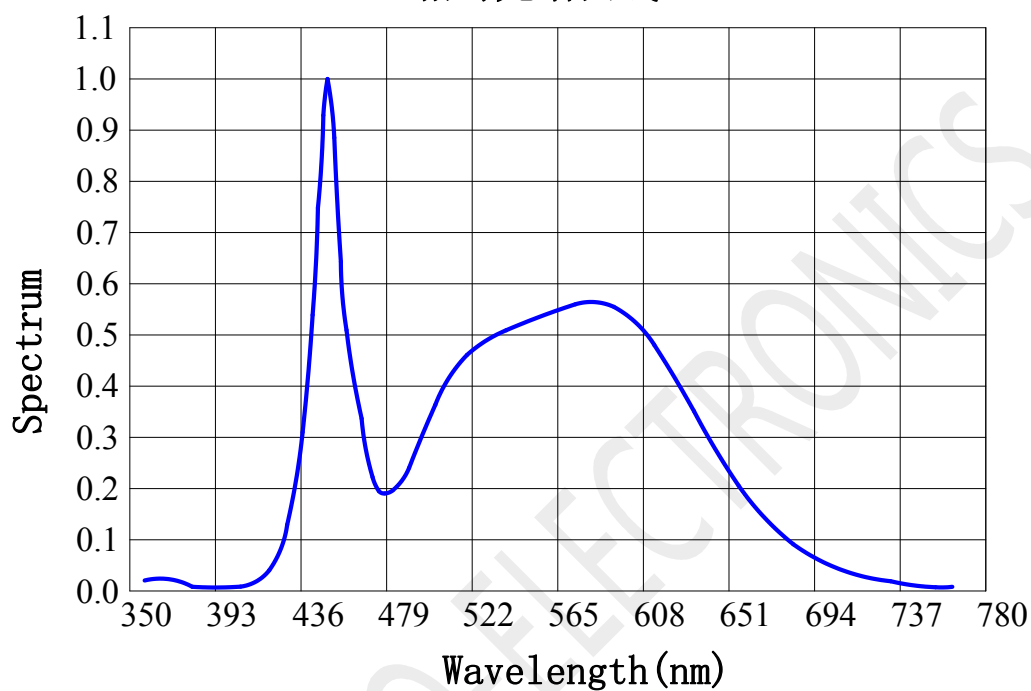
正向电压与正向电流特性曲线



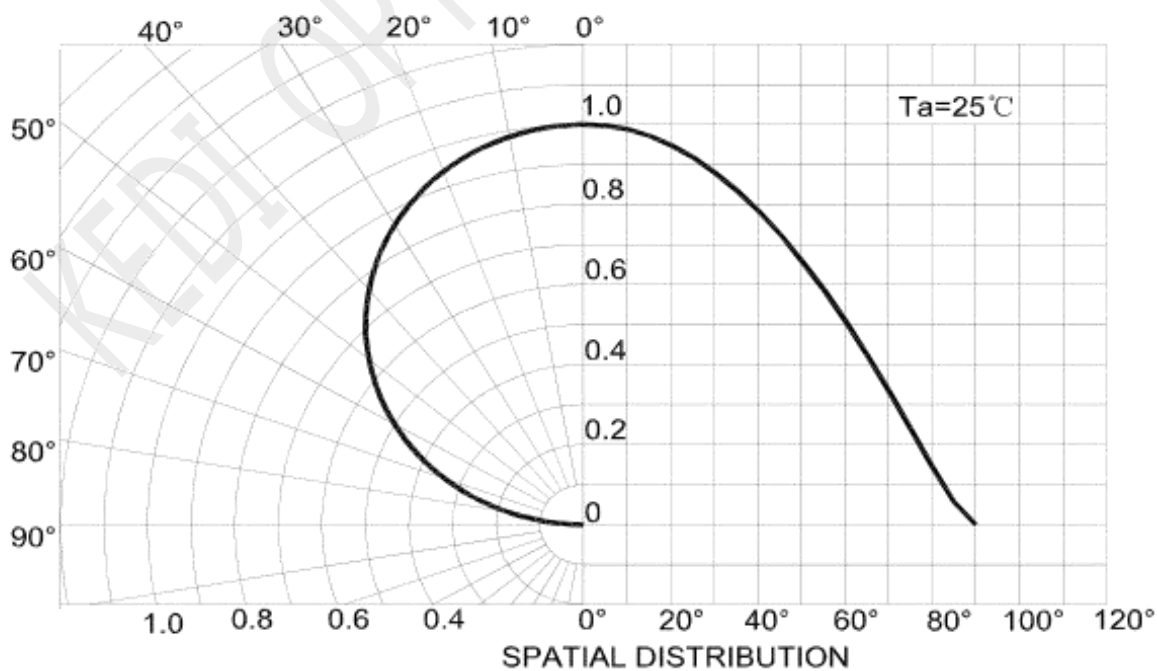
Typical optical characteristics curves 典型光学特性曲线

Relative spectral emission 相对光谱分布特性曲线

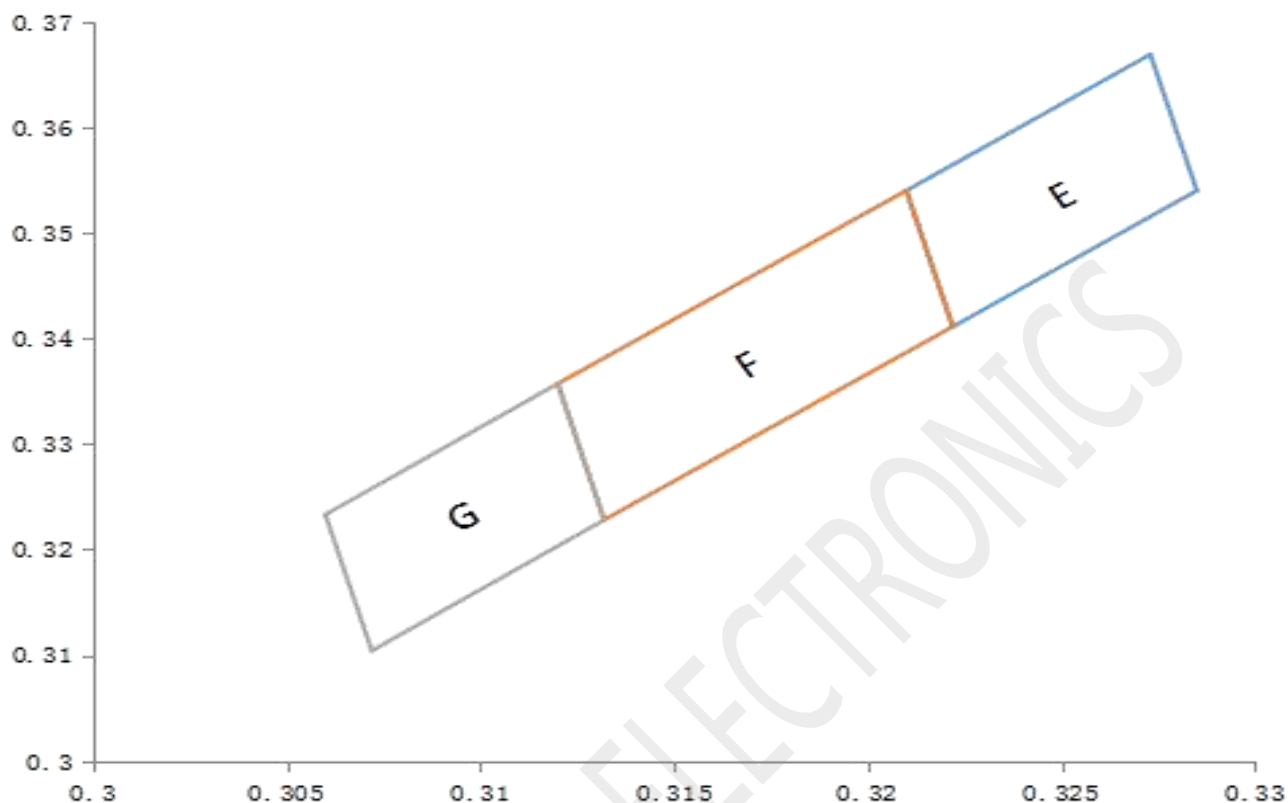
相对光谱曲线



Radiation diagram 辐射图特性曲线



Color coordinates Diagram 色区图:



Bin Range of Chromaticity Coordinate Bin 区分类及色坐标范围:

色区	X0	Y0	X1	Y1	X2	Y2	X3	Y3
E	0.3273	0.3669	0.321	0.354	0.3222	0.3411	0.3285	0.354
F	0.321	0.354	0.312	0.3357	0.3132	0.3228	0.3222	0.3411
G	0.312	0.3357	0.306	0.3233	0.3072	0.3104	0.3132	0.3228

Photoelectric parameters scope of delivey 光电参数出货范围:

voltage Bin List 电压:

(测试条件 Test Condition:20mA)			
Bin No.	Min	Max	UNIT
V22	2.6	2.8	V
V26	2.8	3.0	V
V30	3.0	3.2	V
V34	3.2	3.4	V

Luminous Flux Bin List 光通量:

(测试条件 Test Condition:20mA)			
Bin No.	Min	Max	UNIT
L5	5	6	Lm
L6	6	7	Lm
L7	7	8	Lm

CCT 色温:

(测试条件 Test Condition:20mA)			
Bin No.	Min	Max	UNIT
E	5200	5700	K
F	5700	6300	K
G	6300	7000	K

Reliability 可靠性

Reliability Test Item 可靠性实验项目

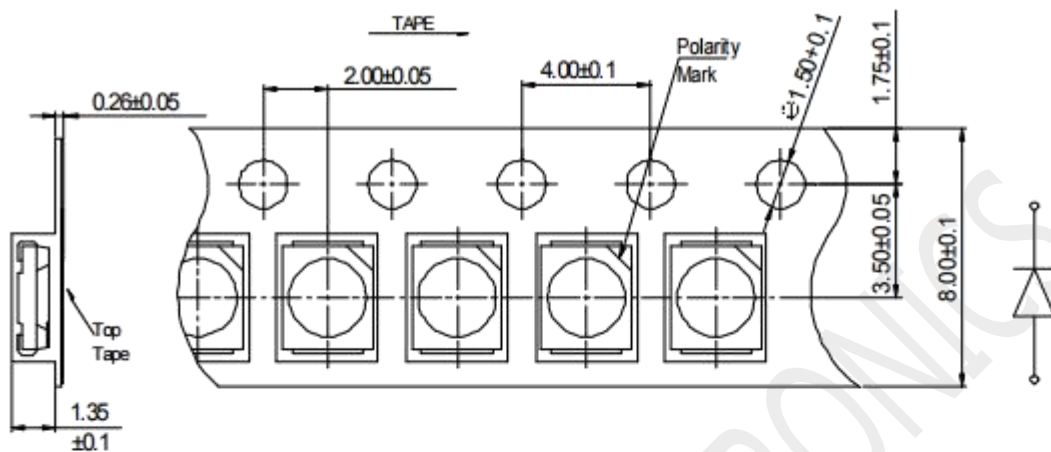
Test Items(测试项目)	Test Conditions(测试条件)	Notes
High Temperature Storage (高温储存)	100℃, 1,000hr.	0/22
Low Temperature Storage (低温储存)	-40℃, 1,000hr.	0/22
Temp. Humidity Storage (高温高湿储存)	H : +100 °C 15min ∩ 5 min L : -40℃ 15min	0/22
Steady State Operating life(常温寿命测试)	25℃, 20mA , 1,000hr.	0/22
High Temperature Operating Life (高温寿命测试)	85℃, 20mA, 1,000hr	0/22
Low Temperature Operating Life (低温寿命测试)	-40℃, 20mA, 1,000hr.	0/22
Steady State Operating life Of High Humidity Heat(高温高湿寿命测试)	85℃, 85% RH, 20mA, 1,000hr.	0/22
Thermal Shock(冷热冲击)	-H : +100 °C 15min ∩ 10 sec L :-40℃ 15min	0/22
ESD(防静电)	HBM, 100 pF, 1.5 kohm, 3 times	0/22

Failure Criteria 失效判定标准

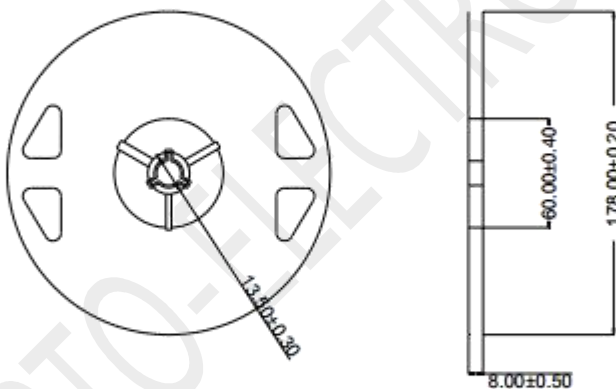
Test Items 项目	Symbol 符号	Test Condition 测试条件	Failure Criteria (判定标准)	
			Min. 最小	Max. 最大
Forward Voltage 正向电压	VF	IF =20mA (1 Chip)	--	U.S.L*)x1.1
Reverse Current 反向电流	IR	VR = 7V (1 Chip)	--	10uA
Luminous Intensity 光强	mcd	IF =20mA (1 Chip)	L.S.L*)x0.8	

U.S.L: Upper Specification Limit 规格上限 L.S.L: Lower Specification Limit 规格下限

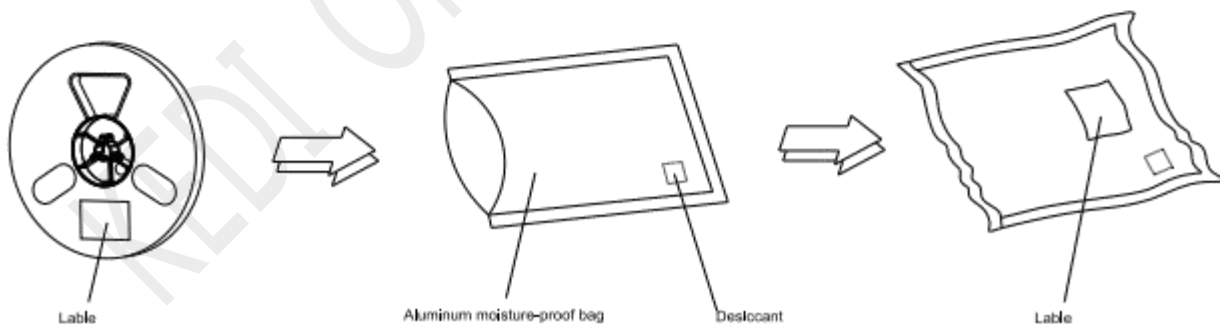
Tape Specifications (Units : mm) 載帶規格 (單位 : mm)



Reel Dimensions

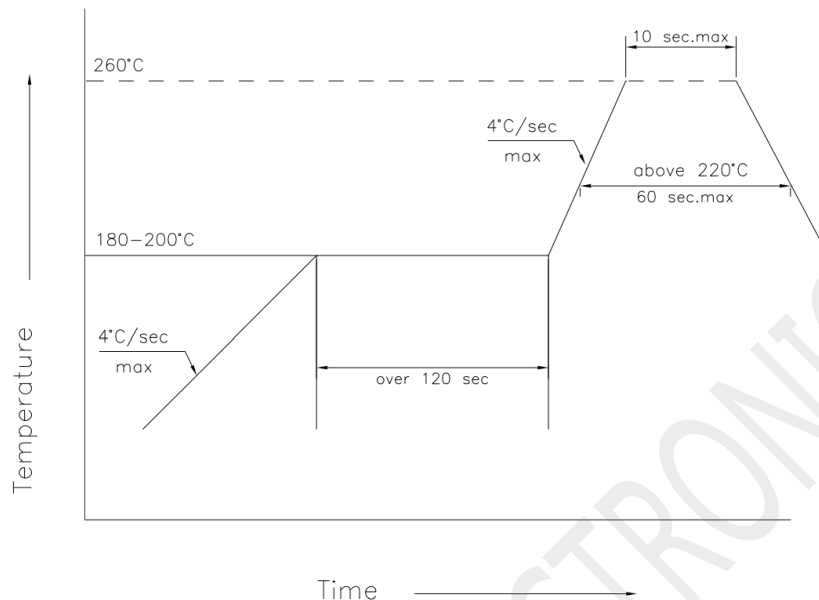


Moisture Resistant Packaging 防潮帶包裝



Note: The tolerances unless mentioned is $\pm 0.1\text{mm}$, Unit: mm 注: 标注公差为 $\pm 0.1\text{mm}$, 单位: mm

SMT Reflow Soldering Instructions SMT 回流焊说明



1. Reflow soldering should not be done more than two times. 回流焊不可以做两次以上

2. When soldering, do not put stress on the LEDs during heating

当焊接时，不要在材料受热时用力压胶体表面

Soldering iron 烙铁焊接

1. When hand soldering, keep the temperature of iron below less 300 °C less than 3 seconds

当手工焊接时，烙铁的温度必须小于 300°C，时间不可超过 3 秒

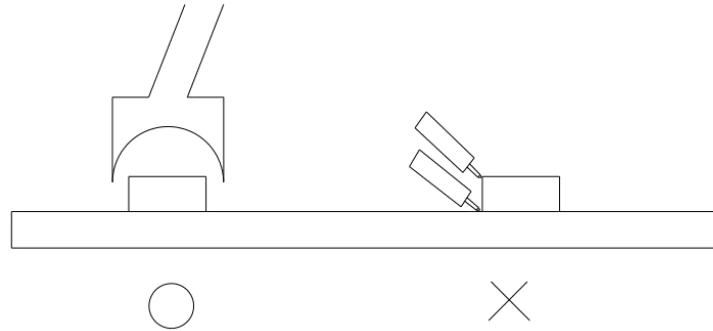
2. The hand solder should be done only one times

手工焊接只可焊接一次

Repairing 修补

Repair should not be done after the LEDs have been soldered. When repairing is unavoidable, a double-head soldering iron should be used (as below figure). It should be confirmed in advance whether the characteristics of LEDs will or will not be damaged by repairing.

LED 回流焊后不应该修复，当修复是不可避免时，必须使用双头烙铁（如下图），但必须事先确认此种方式会或不会损坏 LED 本身的特性。



Cautions 注意事项

The encapsulated material of the LEDs is silicone. Therefore the LEDs have a soft surface on the top of package. The pressure to the top surface will be influence to the reliability of the LEDs. Precautions should be taken to avoid the strong pressure on the encapsulated part. So when use the picking up nozzle, the pressure on the silicone resin should be proper.

LED 封装为硅胶，故 LED 胶体表面较软，用力按压胶体表面会影响 LED 可靠性，因此应有预防措施避免在封装的零件上的强大压力，当使用吸嘴时，胶体表面的压力应是恰当的

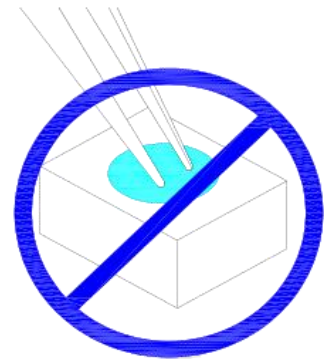
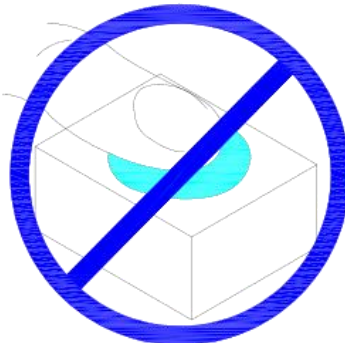
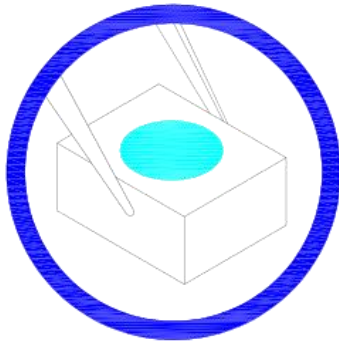
Handling Precautions 处理防备措施

Compare to epoxy encapsulant that is hard and brittle, silicone is softer and flexible. Although its characteristic significantly reduces thermal stress, it is more prone to damage by external mechanical force . As a result, Special handling precautions must be observed during assembling using silicone encapsulated LED products, Failure to comply might leads to damage and premature failure of the LED.

相对环氧树脂较脆较硬而言，硅胶封装较柔软且有弹性，虽然它的特性大大减少了热应力，但易受机械外力损坏，因此在手工处理方面须要对硅胶封装材料做预防措施，若未按要求操作，可能会导致 LED 损坏和光衰

1.Handle the component along the side surface by using forceps or appropriate tools; do not directly touch or Handle the silicone lens surface, it may damage the internal circuitry.

通过使用适当的工具从材料侧面夹取，不可直接用手或尖锐金属压胶体表面，它可能会损坏内部电路



2.The outer diameter of the SMD pickup nozzle should not exceed the size of the LED to prevent air leaks. The inner diameter of the nozzle should be as large as possible. A pliable material is suggested for the nozzle tip to avoid scratching or damaging the LED surface during pickup. The dimensions of the component must be accurately programmed in the pick-and-place machine to insure precise pickup and avoid damage during production.

为防止气压泄漏，SMD 吸咀外径不可以超过 LED 尺寸，吸咀内径尺寸应尽可能大，吸咀顶端材质建议采用柔软材料以防在吸取期间刮伤或损坏 LED 胶体表面，元件的尺寸必须在取放机里准确的编程好，以确保精确的吸取和避免生产过程中的损害



3.Do not stack together assembled PCBs containing LEDs. Impact may scratch the silicone lens or damage the internal circuitry 不可将模组材料堆积在一起，它可能会损坏内部电路

4.Not suitable to operate in acidic environment, PH<7 不可用在 PH<7 的酸性场所

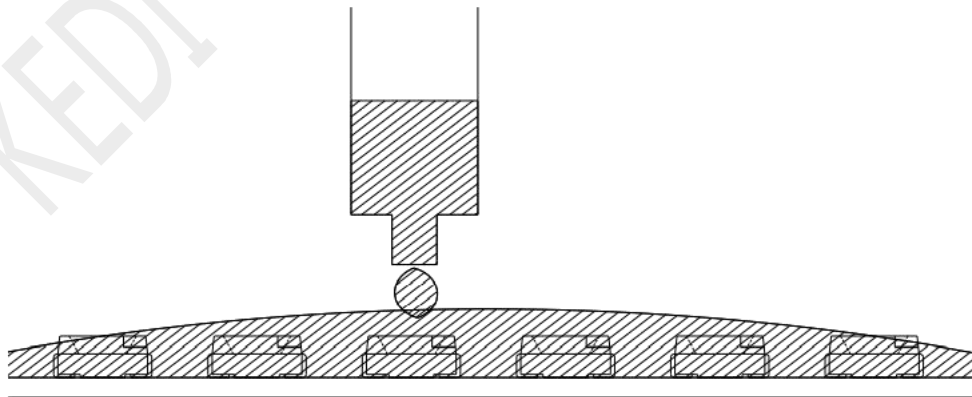


5.LED operating environment and sulfur element composition cannot be over 100PPM in the LEDmating usage material .

LED 工作环境及与 LED 适配的材料中硫元素及化合物成份不可超过 100PPM

6.When we need to use external glue for LED application products, please make sure that the external glue matches the LED packaging glue. Additionally ,as most of LED packaging glue is silica gel, and it has strong Oxygen permeability as well as strong moisture permeability; in order to prevent external material from getting into the inside of LED, which may cause the malfunction of LED, the single content of Bromine element is required to be less than 900PPM,the single content of Chlorine element is required to be less than 900PPM,the total content of Bromine element and Chlorine element in the external glue of the application products is required to be less than 1500PPM

当我们需要使用外封胶涂抹 LED 产品时，应确保外封胶与 LED 封装胶水相匹配，因为大多数 LED 的封装胶水为硅胶，它有较强的氧化性和较强的吸湿性，必须防止外封材质进入 LED 内部以造成 LED 的损伤，单一的溴元素含量要求小于 900PPM，单一氯元素含量要求小于 900PPM，在涂抹 LED 产品时要求外封胶溴元素与氯元素总含量必须小于 1500PPM



7.Other points for attention, please refer to our LED user manual.

其它注意事项请参照我们的 LED 使用手册